

Harsh Environment Sensor Cluster for Infrastructure Monitoring

Single-Chip, Self-Powered, Wireless Sensor Systems



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Harsh Environment Sensor Cluster

The National Science Foundation
Industry/University Cooperative Research Center on MEMS




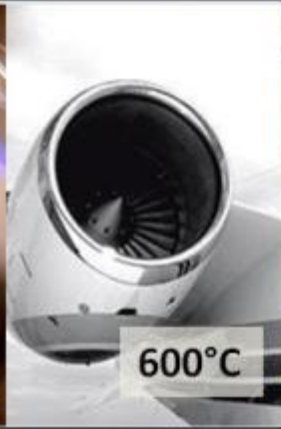



*“BSAC conducts **industry-relevant, interdisciplinary research on micro- and nano-scale sensors, moving mechanical elements, microfluidics, materials, and processes, and systems that take advantage of progress from integrated circuit, networking, bio, and polymer technologies.**”*



Cluster Sensor for Energy & Power

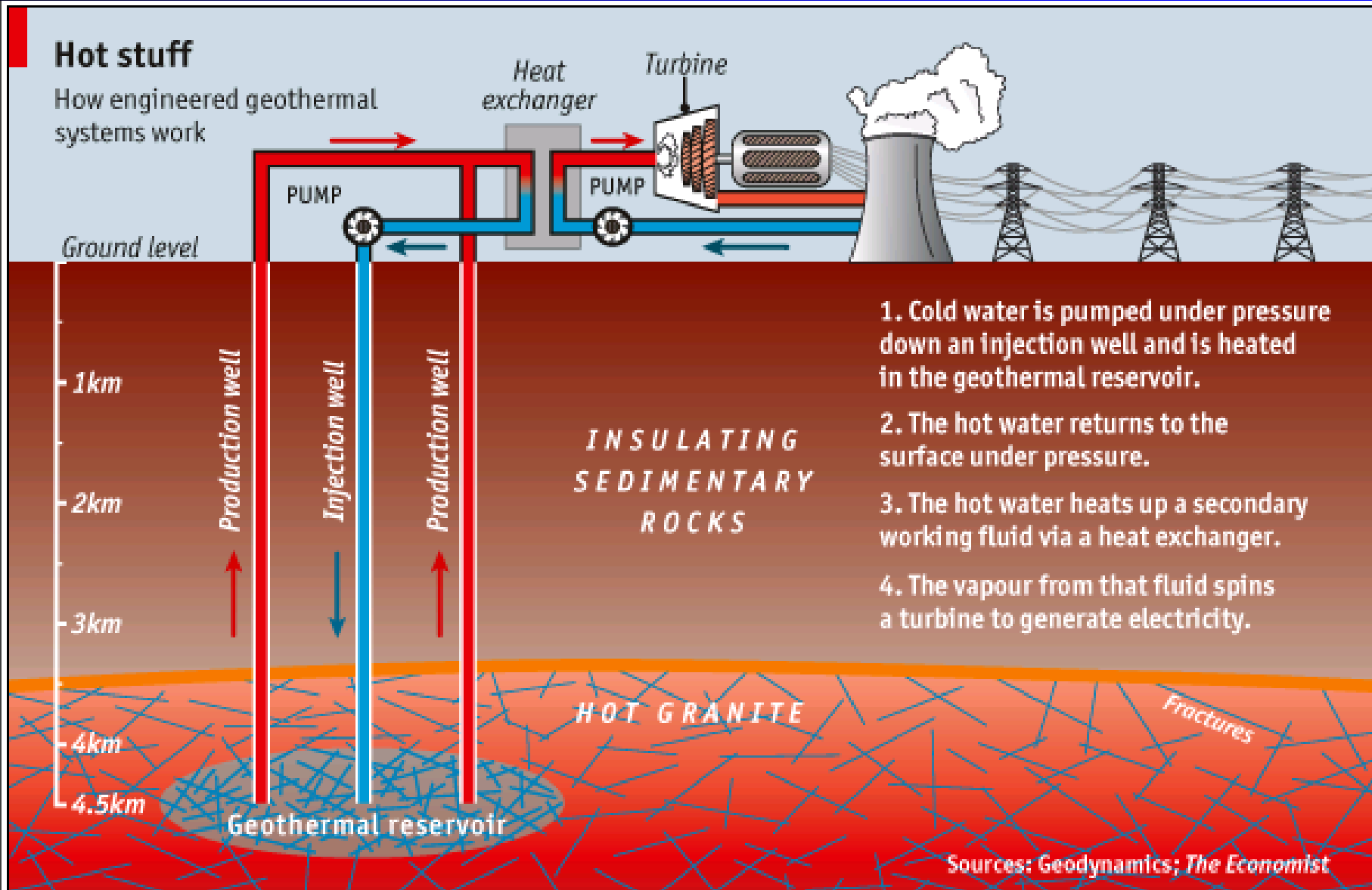
Harsh Environment Sensor Cluster

Energy Industries	Geothermal	Oil & Gas Exploration	Industrial Gas Turbines	Aircraft Engines	Automotive Engines
Required Sensing Temperatures	 375°C	 275°C	 600°C	 600°C	 300°C
Desired Sensing Measurands	<ul style="list-style-type: none"> • Pressure • Temperature • H₂S • Strain 	<ul style="list-style-type: none"> • Pressure • Temperature • Hydrocarbon • Strain 	<ul style="list-style-type: none"> • Pressure • Temperature • Flame speed • Acceleration 	<ul style="list-style-type: none"> • Pressure • Temperature • Flame speed • Acceleration 	<ul style="list-style-type: none"> • Pressure • Temperature • Flame speed • O₂

- “Harsh environment” includes extremes of pressure, temperature, shock, radiation and chemical attack.
- Real-time sensing within harsh environments enables increased operation lifetimes, improved efficiency and reduced emissions.

Geothermal Energy

Harsh Environment Sensor Cluster



Geothermal Resources in Japan

Harsh Environment Sensor Cluster

List of Geothermal Power Plants in Japan

Mori	Ohnuma	Sumikawa
Matsukawa	Kakkonda	Uenotai
Onikobe	Yanaizu-Nishiyama	Hachijo-Jima
Suginoi	Takigami	Ohdake
Hatchobaru	Ohgiri	Kirishima-kokusai Hotel
Yamagawa	Kuju	



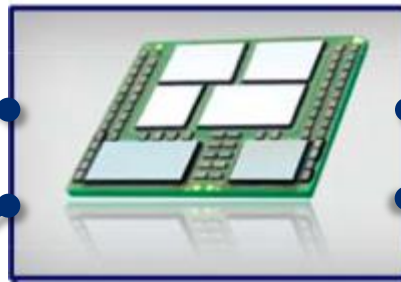
Source:

http://wwwsoc.nii.ac.jp/grsj/geothermalinJ/Res&PP/P_Plant/main121.html

Sensor Cluster in the Ground

Harsh Environment Sensor Cluster

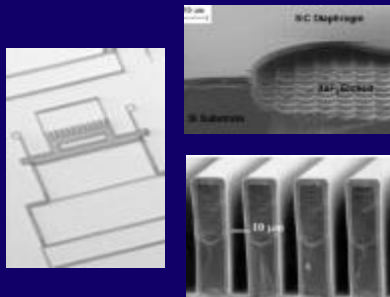
Self-powered, Wireless, Multi-Chip Sensing Module



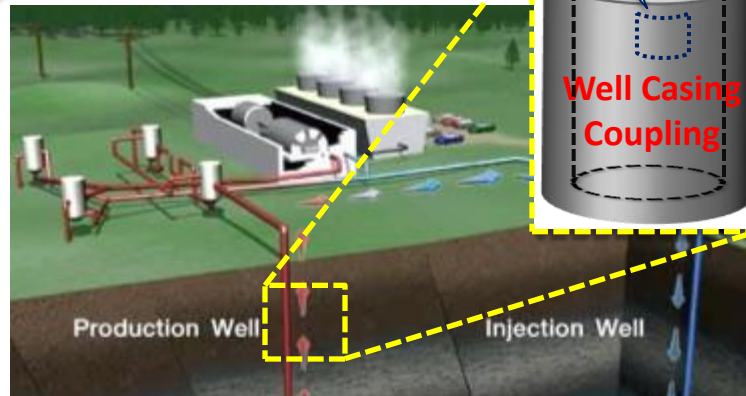
SiC Integrated
Circuits



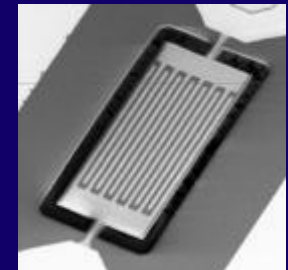
SiC/AlN Scavenging
Power Source



SiC/AlN Harsh
Environment Sensors



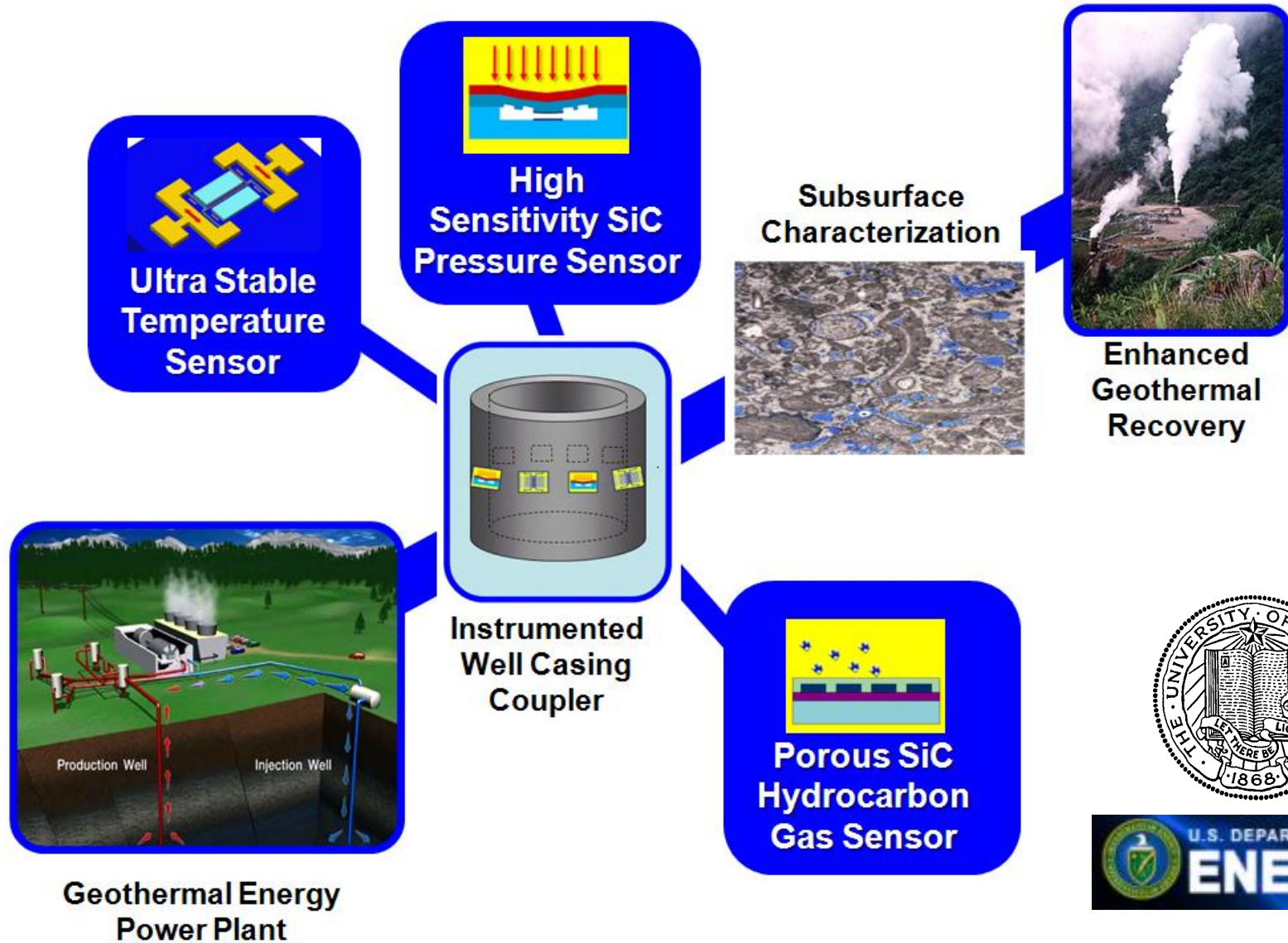
**Efficient, Clean & Smart
Geothermal Energy Systems**



AlN RF Telemetry
Components

Cluster Sensor in the Ground

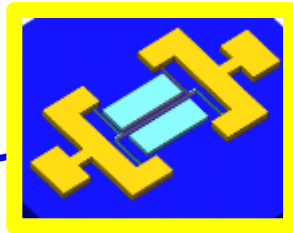
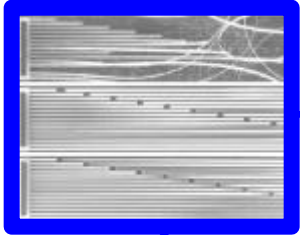
Harsh Environment Sensor Cluster



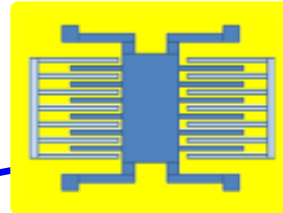
Cluster Sensor in the Gas Turbine

Harsh Environment Sensor Cluster

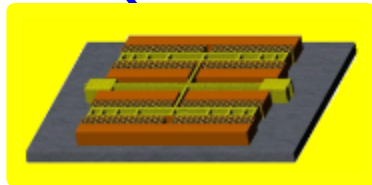
SiC Materials
Development and
Characterization



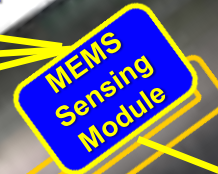
Ultra-Stable
Temperature
Sensor



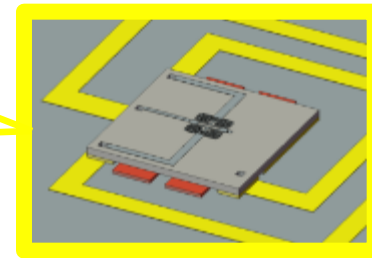
Ultra Low Cross Axis
Sensitivity
Accelerometer



High Accuracy
Erosion/Corrosion
Sensor



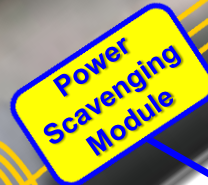
MEMS
Sensing
Module



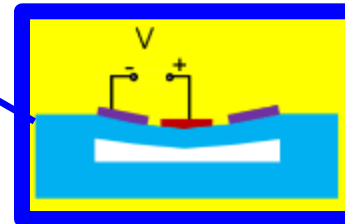
High Temperature
Bonding and
Interconnect



RF
Module



Power
Scavenging
Module



AlN Energy
Scavenging Diaphragm

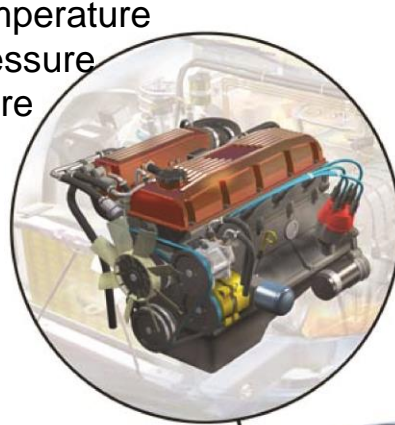
Gas
Turbine
Blade

Cluster Sensor for Transportation

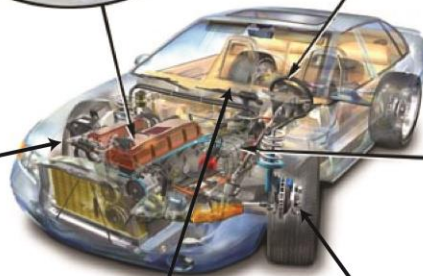
Harsh Environment Sensor Cluster

- Combustion chamber temperature
- Combustion chamber pressure
- Manifold absolute pressure
- Mass air flow sensor
- Oxygen sensor
- Exhaust NO_x sensor

- Pressure sensors
- Accelerometer array

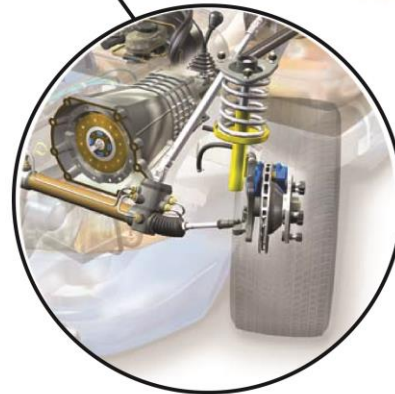
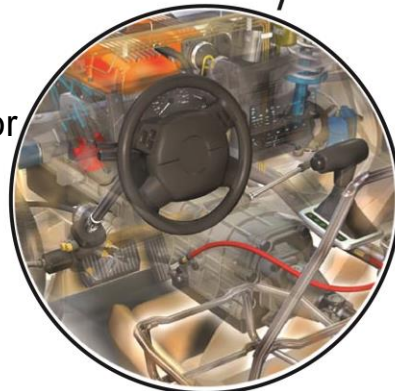


- Steering wheel angle sensor
- Front airbag accelerometer
- Steering circuit oil pressure
- Brake circuit oil pressure



- Transmission torque
- Halfshaft torque

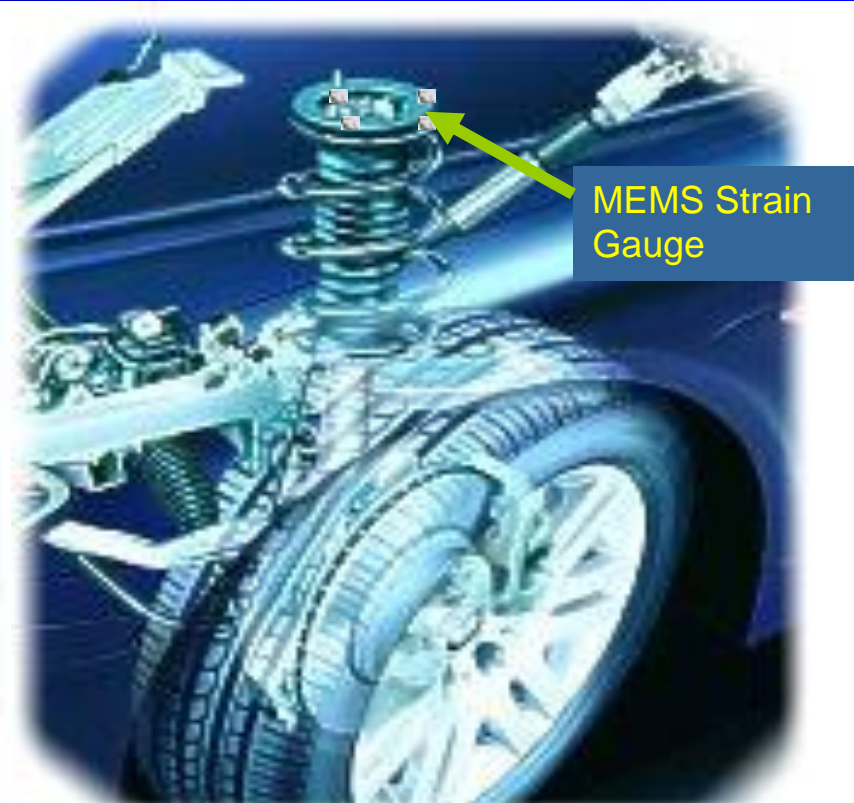
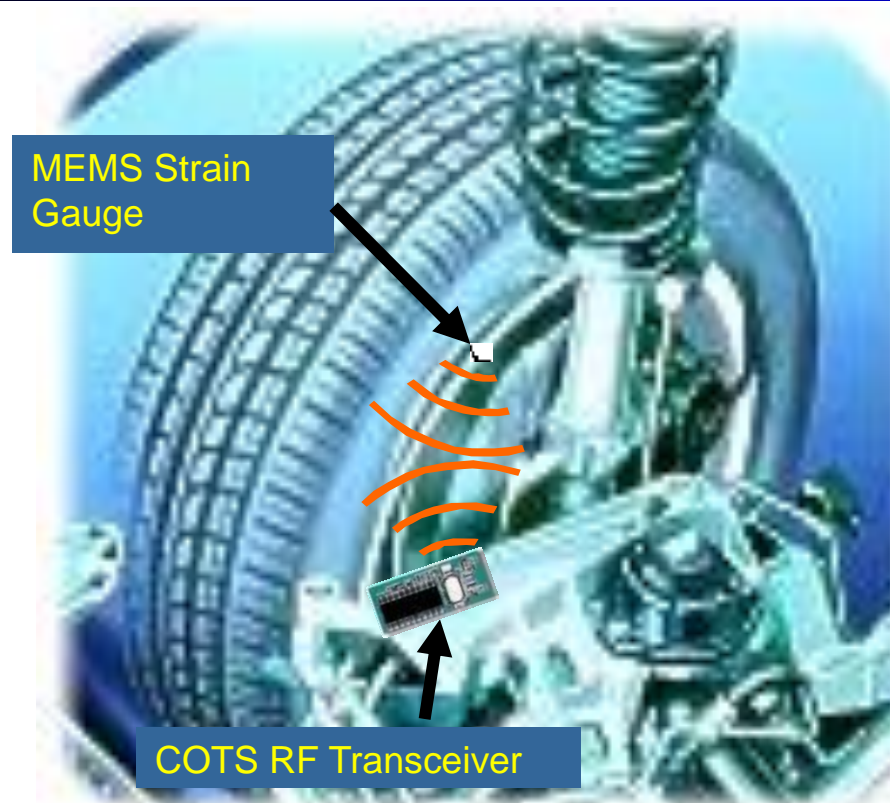
- Airbag accelerometers
- Air quality filtration sensor
- Rain sensor
- Passenger temperature
- Pedal position sensor



- Angular rate (roll over)
- Chassis tilt sensor
- Wheel speed rate (ABS)
- Wheel torque sensor
- Active suspension sensor

Sensor Cluster in the Automobile

Harsh Environment Sensor Cluster

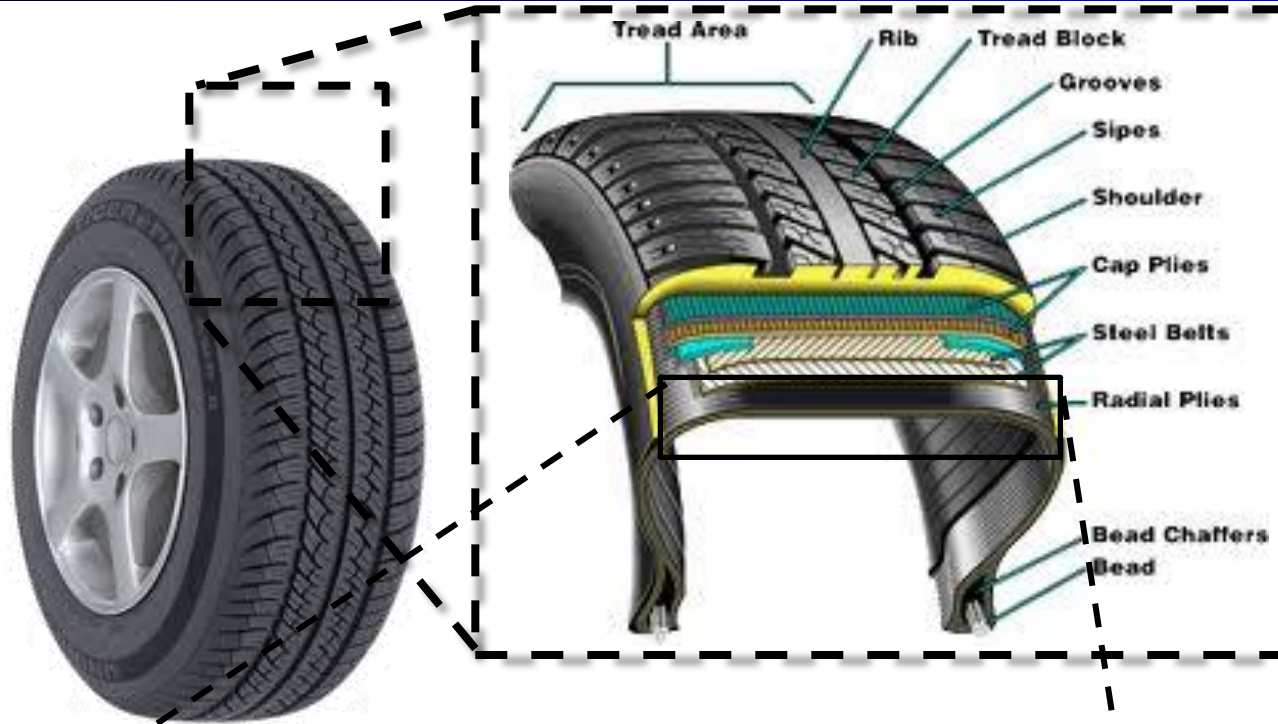


- MEMS Sensor on Wheel Communicates via RF to Transceiver on Chassis

- MEMS Sensor on Shock Tower Measures Vertical Forces On Chassis for DSC Application

Sensor Cluster in the Tire

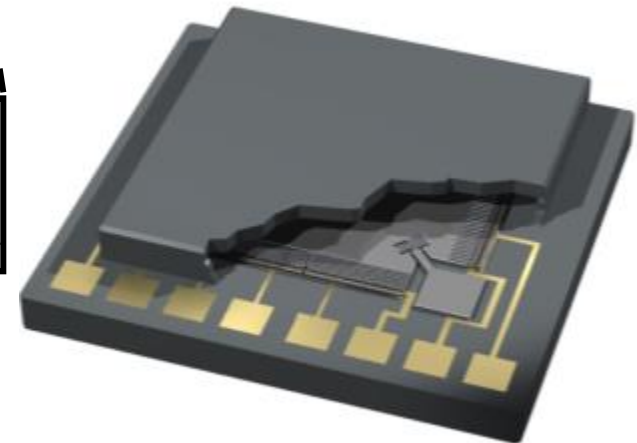
Harsh Environment Sensor Cluster



Sensor Types:
Strain Sensors
Pressure Sensors
Accelerometers



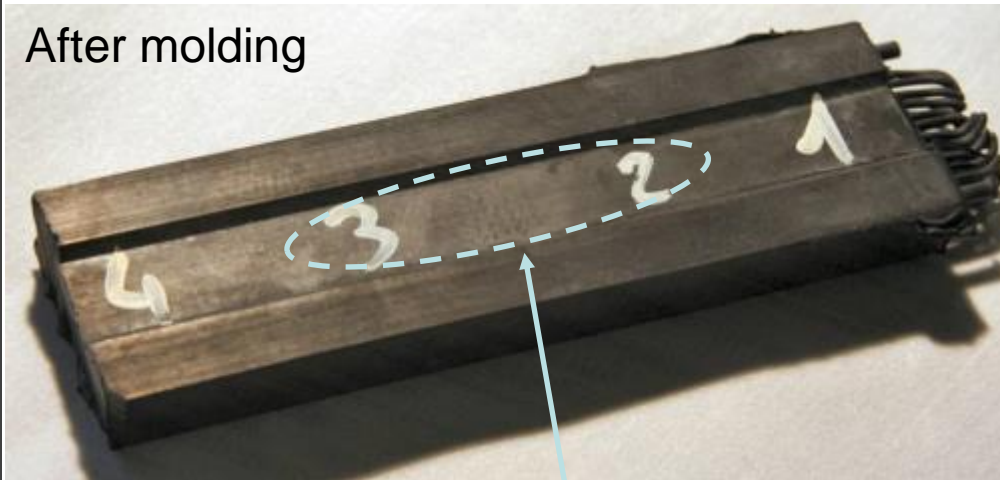
3-Point Array of Sensors



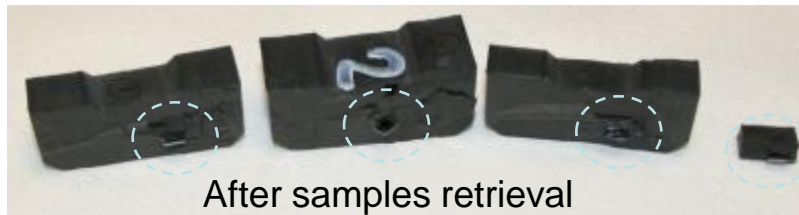
Molding & Vulcanization

Harsh Environment Sensor Cluster

After molding



Embedded samples

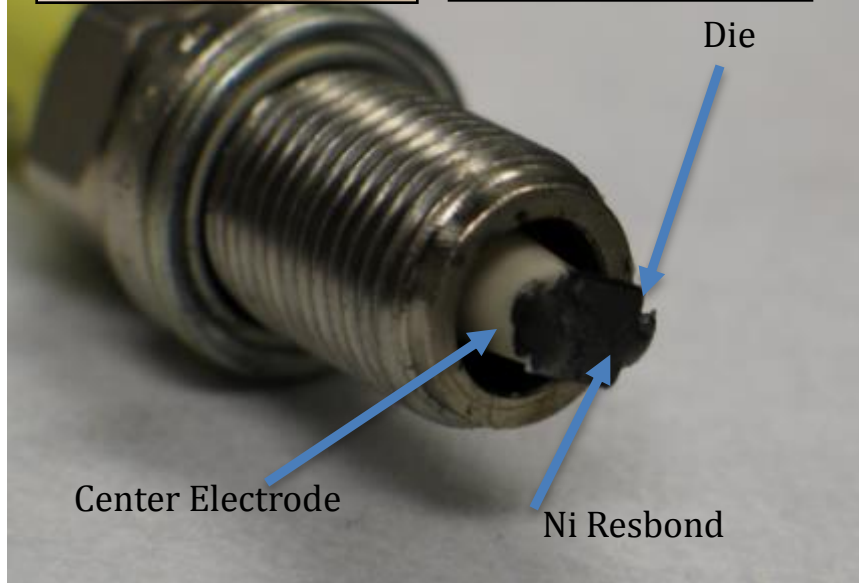


After samples retrieval

- 4 embedded samples
- 5x5mm² each
- Array of SiC Zener diodes
 - Survivability test
- Si substrate covered with SiO₂/SiC
 - Delamination test
- Two Si substrates
 - Bare Si
 - Si + Ni (2nm)
 - → Sample/rubber adhesion

Cluster Sensor in the Auto Engine

Harsh Environment Sensor Cluster



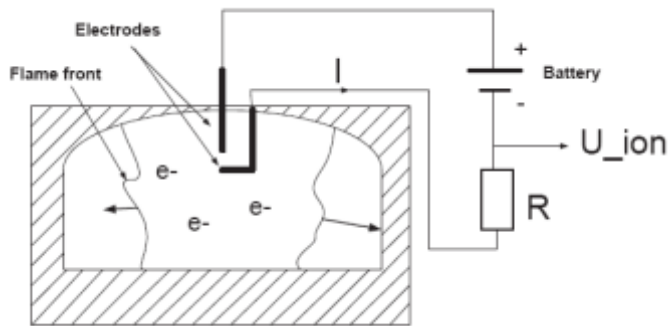
Test Fixture for signal collection. There are two die attachment methods:

1) Simultaneous Electrical and Mechanical Attachment via Ni Resbond with Auxiliary Mechanical Attachment via Ceramic Adhesive

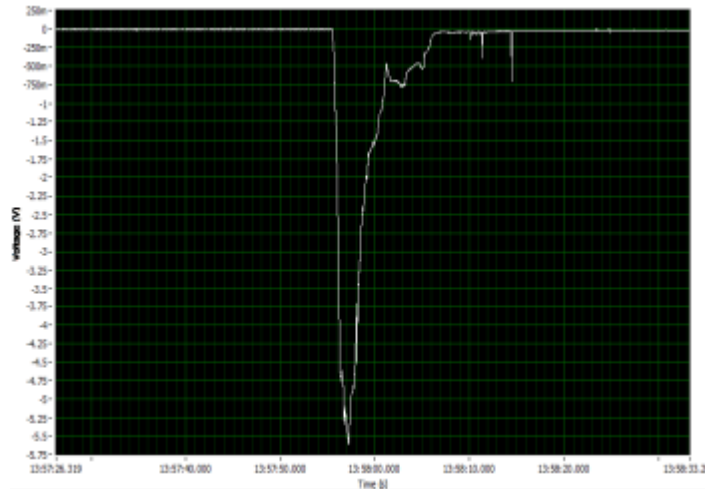
2) Separate Electrical and Mechanical Attachment via Ceramic Adhesive for Mechanical and Aluminum Wire Bonds for Electrical

Cluster Sensor in the Auto Engine

Harsh Environment Sensor Cluster

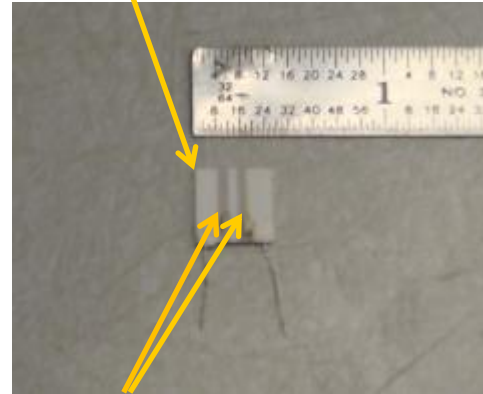


Bias voltage \rightarrow leakage current \rightarrow ion concentration detection



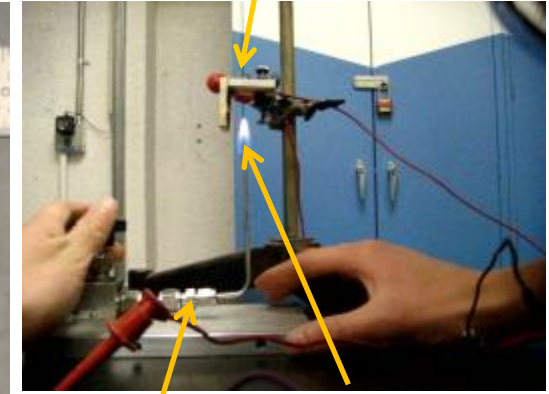
5.5V peak signal (from 120V bias voltage). Expecting **< 0.010V resolution**.

1 cm² fired alumina substrate



Sintered Pt electrodes (1mm wide, 1mm gap)

Ceramic shield to protect wire leads



Controlled flame jet

Methane diffusion flame

Prototype fabricated and tested:

- Platinum ink on alumina substrate
- Preliminary tests show geometry has good sensitivity to flames

Next steps:

- Production via MEMS or microprinting technology
- Design and construction of test chamber

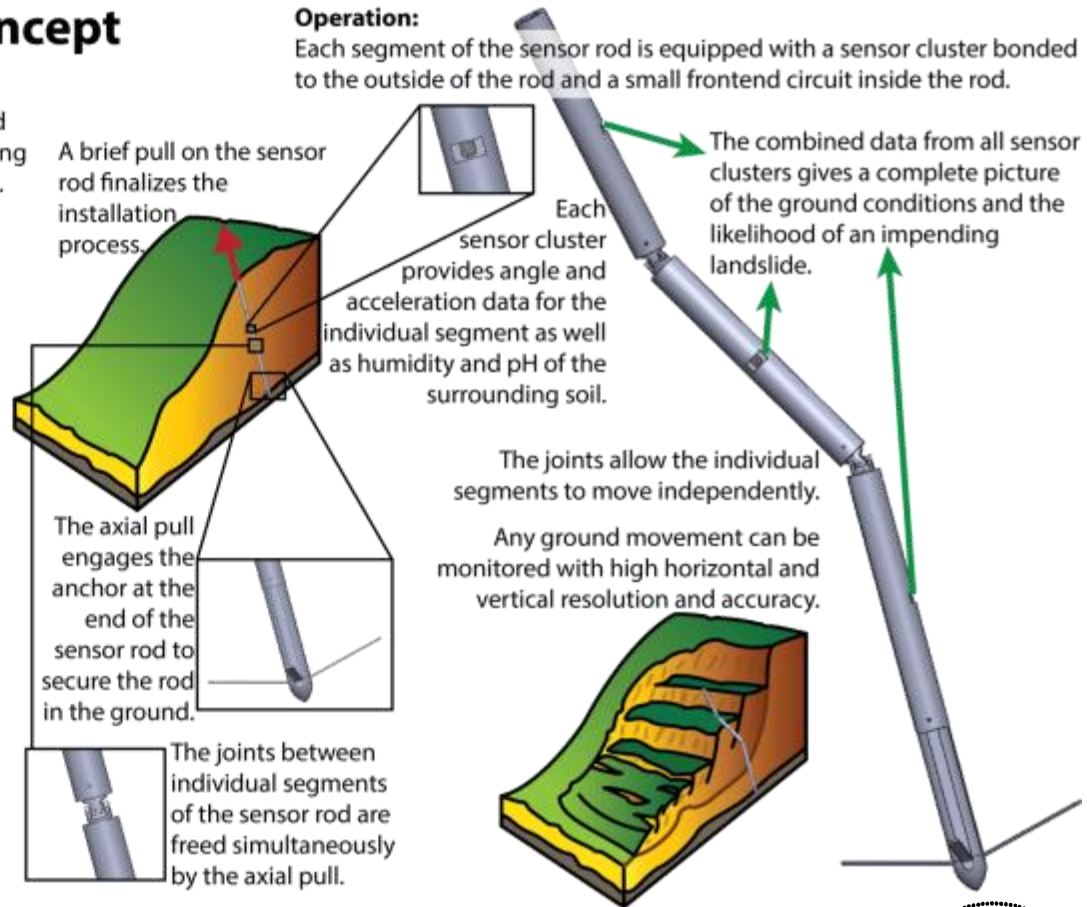


Cluster Sensor Landslide Prediction



Harsh Environment Sensor Cluster

Landslide Sensor Rod Concept



Cluster Sensor for Infrastructure

Harsh Environment Sensor Cluster

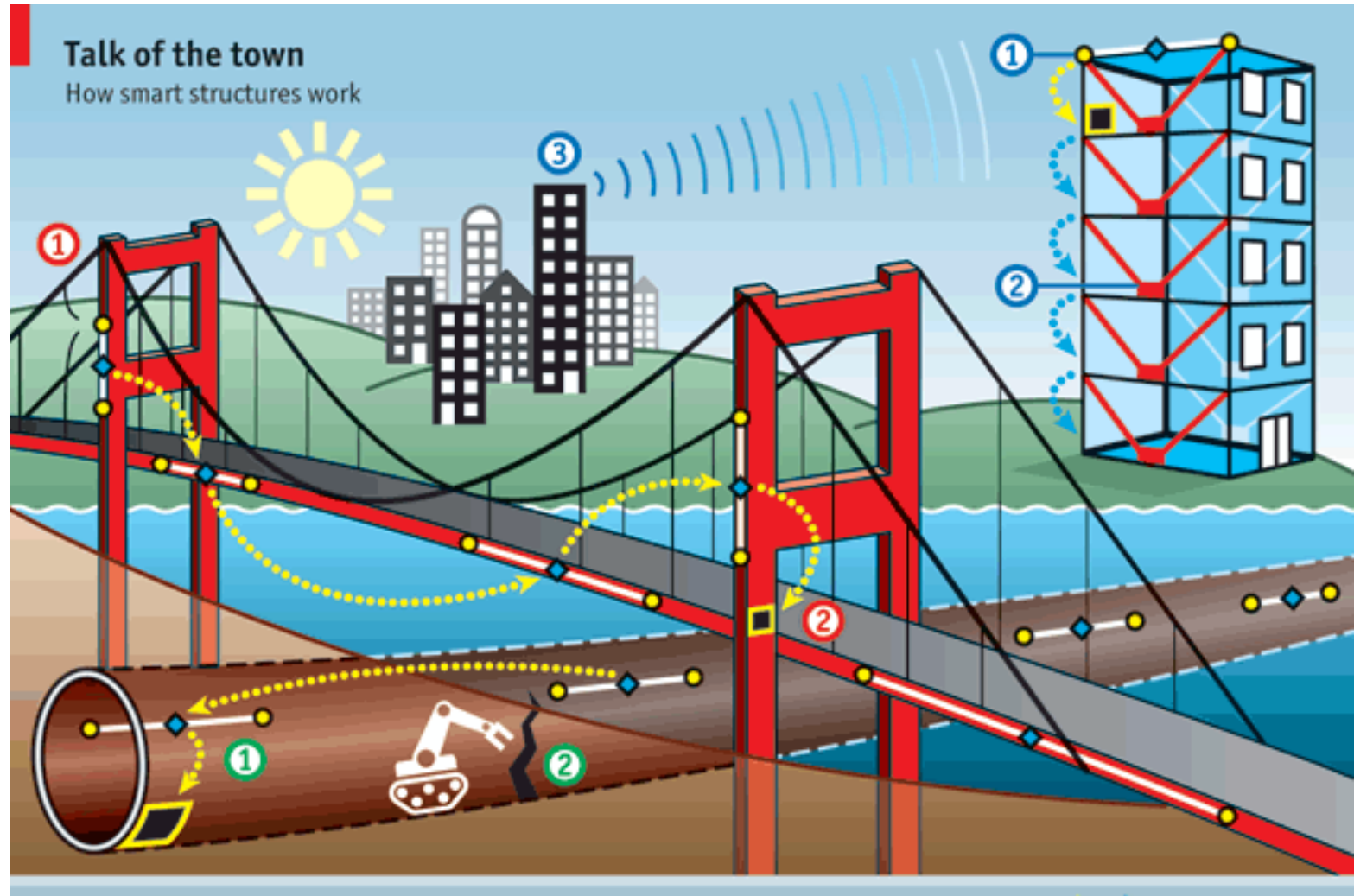
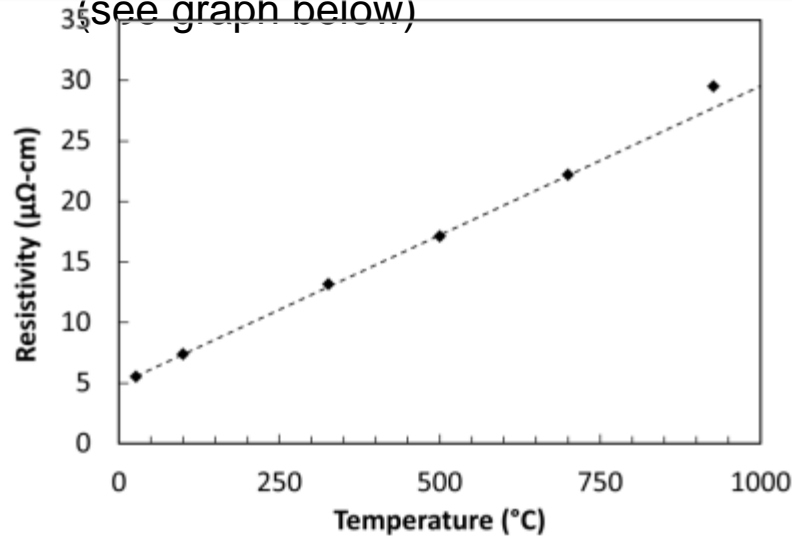


Figure from The Economist Magazine

Sensor Cluster Prototype

Harsh Environment Sensor Cluster

- Temperature sensor is resistive type (resistance changes linearly with temperature)
- Sensor size can be very small (e.g. 200 μm x 200 μm)
- Many temperature sensors can be placed on the sensor cluster chip
- Linearity is very good for Molybdenum in the required temperature range (see graph below)



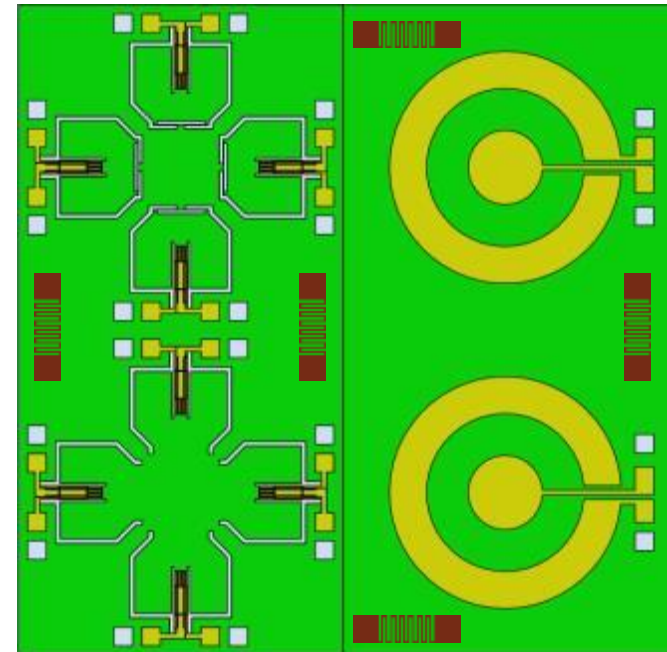
Source: www.elmettechnologies.com

Example of Sensor Design



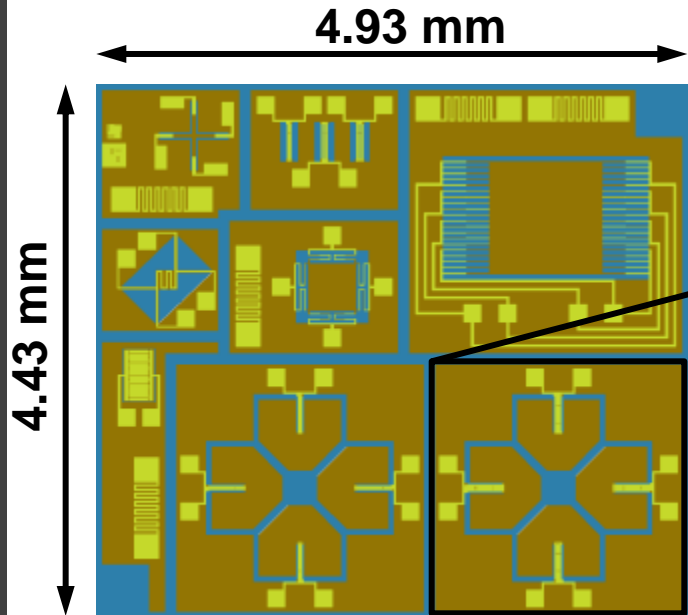
Example of Placement

Note: This is a schematic figure. The actual design of the prototype 1 chip will be submitted later.

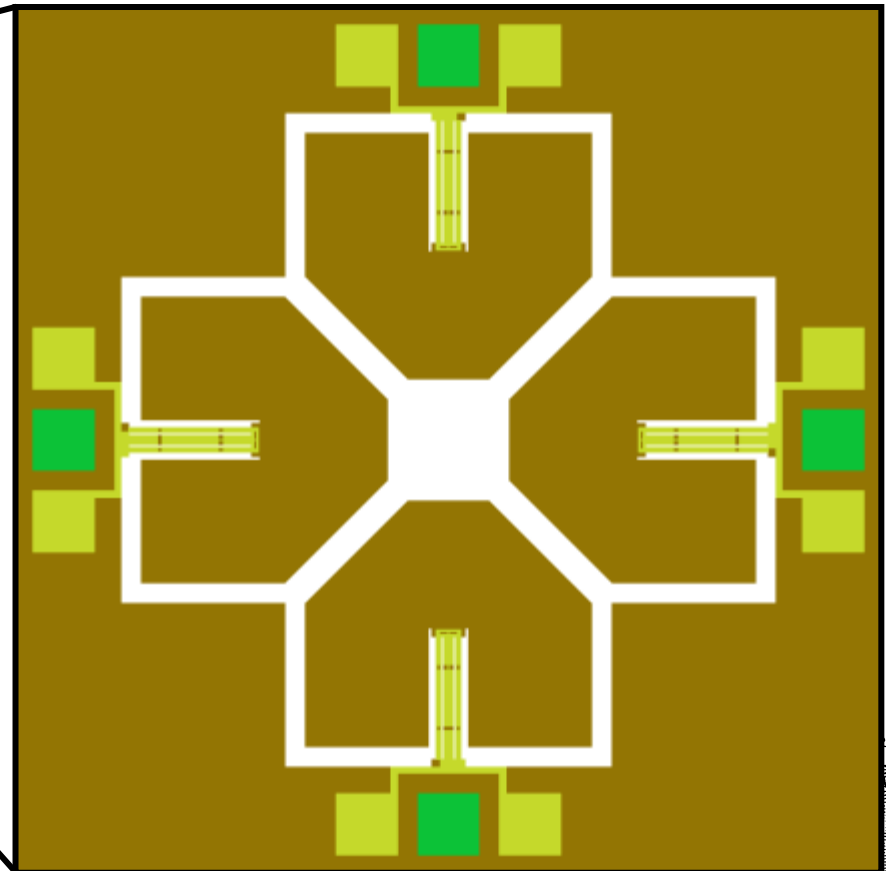


Pre-Prototype Design

Harsh Environment Sensor Cluster



2-Axis Accelerometer

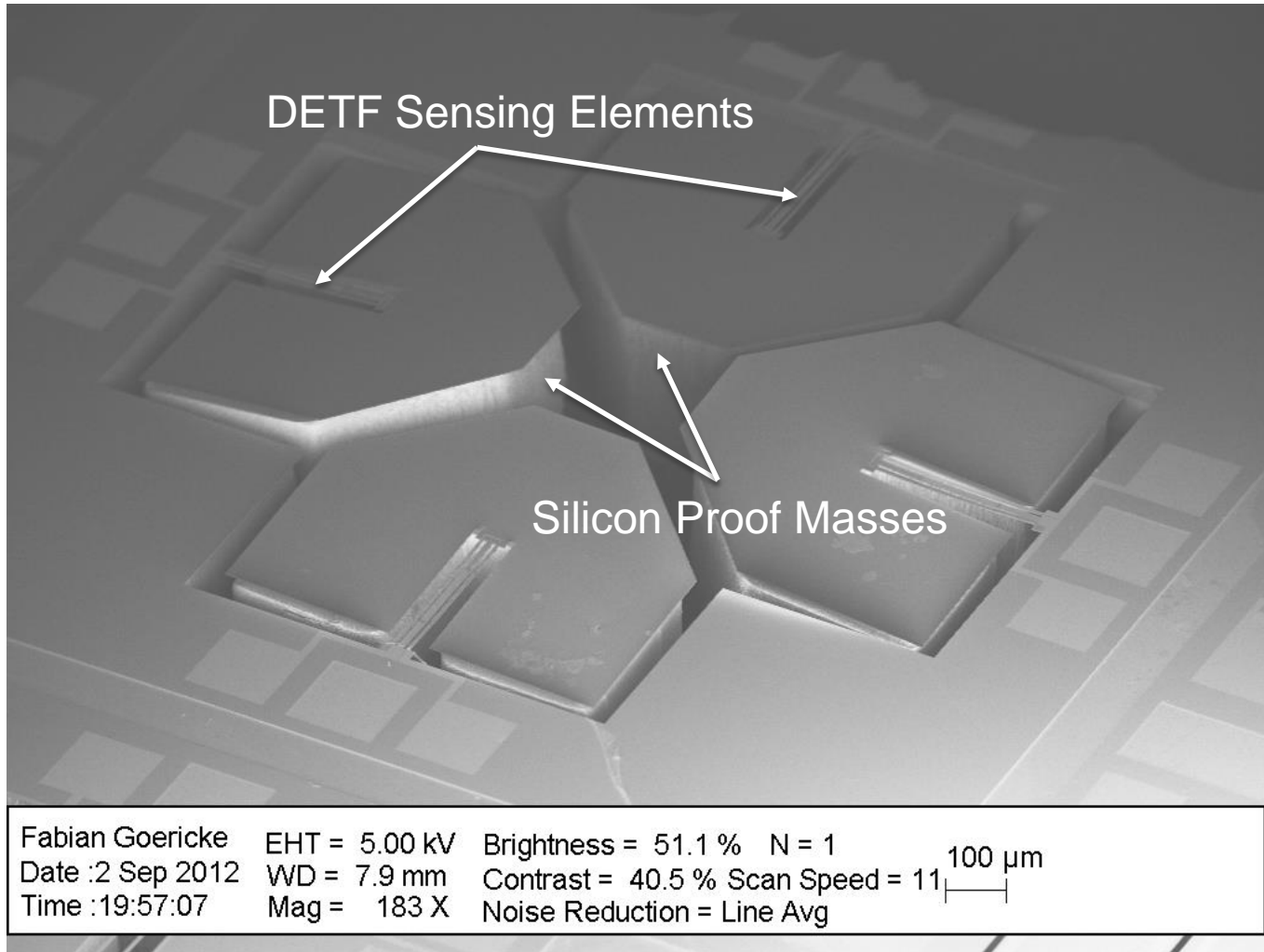


Integrated components:

- 2-axis accelerometer
- Vacuum pressure gauge
- Strain sensor
- Temperature sensor

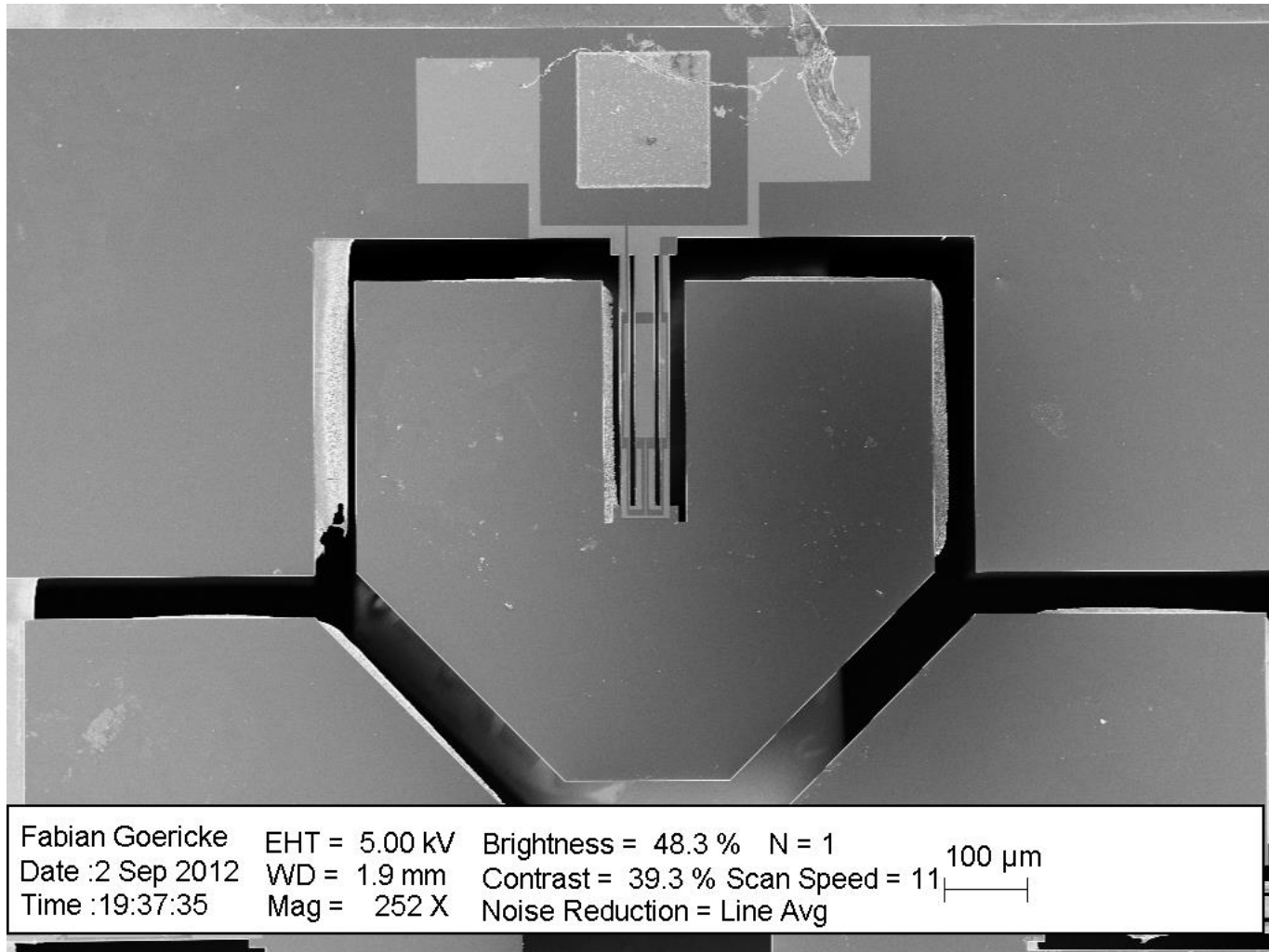
Pre-Prototype Results

Harsh Environment Sensor Cluster



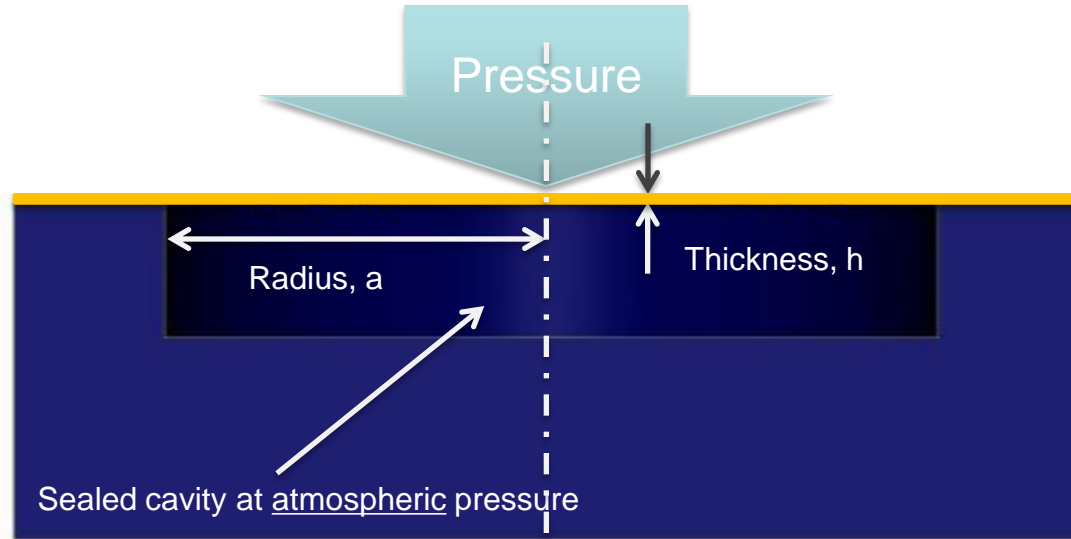
Pre-Prototype Results

Harsh Environment Sensor Cluster



AIN Pressure Sensor Design

Harsh Environment Sensor Cluster



Characteristic Equation for
Circular Membrane:

$$\frac{Pa^4}{Eh^4} = 5.86 \frac{y}{h} + 3.19 \frac{y^3}{h^3}$$

Resonance frequency of membrane:

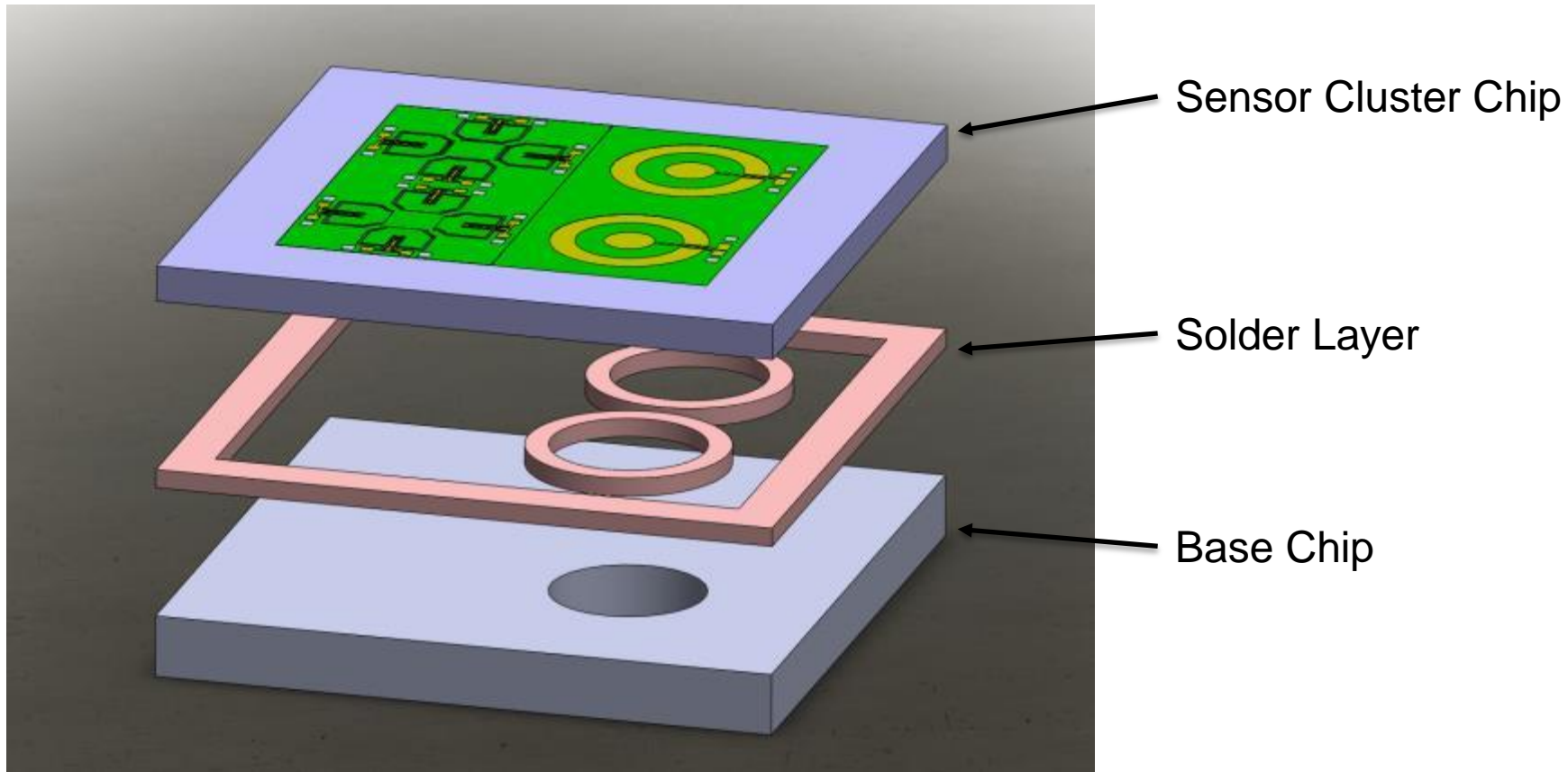
$$\omega = 9.22 \frac{h}{a^2} \sqrt{\left[\frac{E}{\rho(1 - \mu^2)} \right]}$$

a = radius, b = thickness, y = deflection, E = Young's modulus, A_e = effective area of corrugated diaphragm, D = flexural rigidity, μ = Poisson's ratio, ρ = specific weight of membrane material.



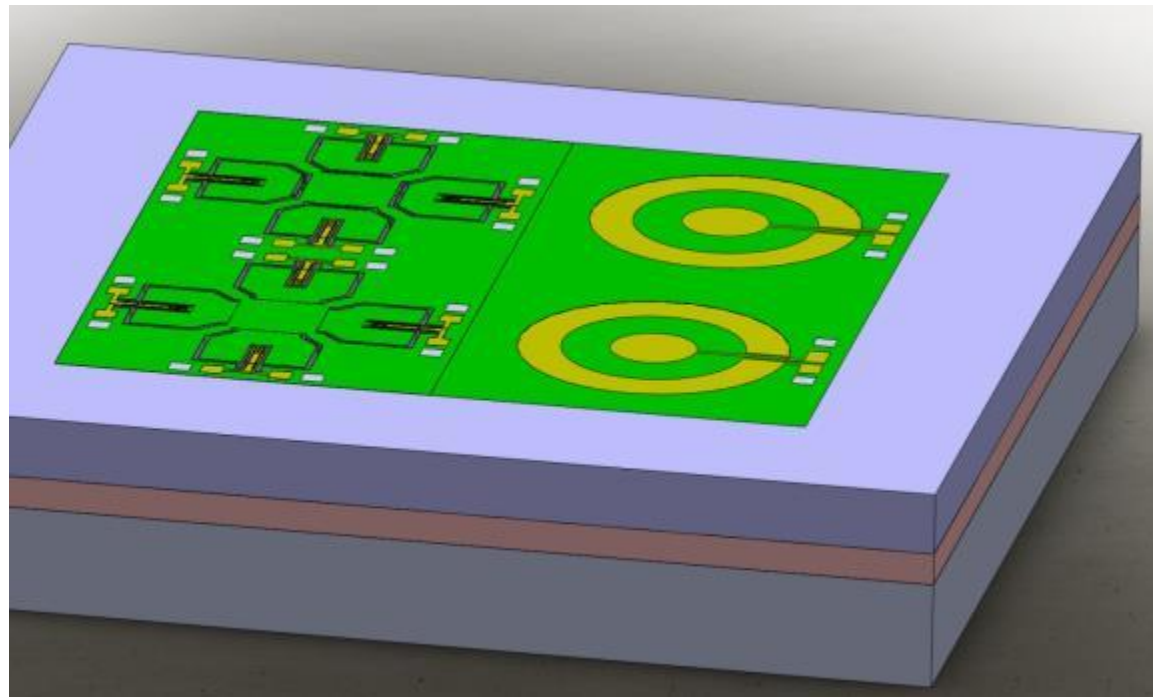
Cluster Prototype Assembly

Harsh Environment Sensor Cluster



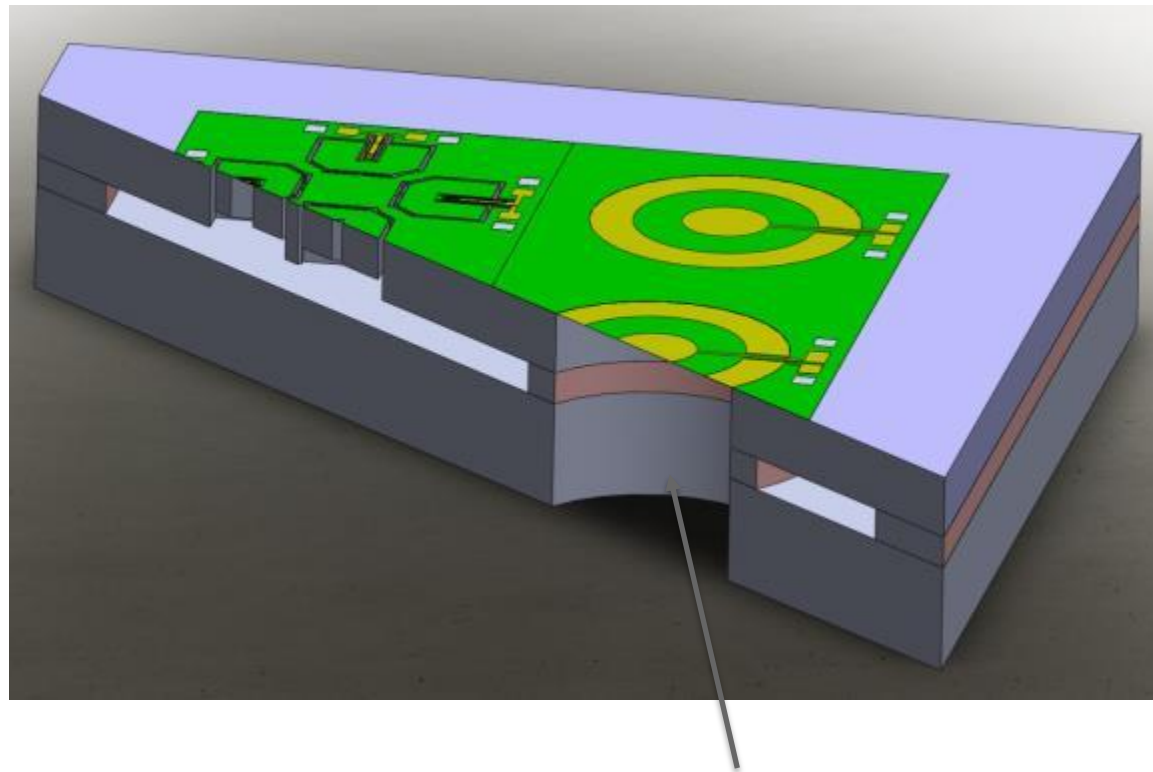
Cluster Prototype Assembly

Harsh Environment Sensor Cluster

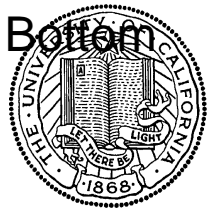


Cluster Prototype Assembly

Harsh Environment Sensor Cluster

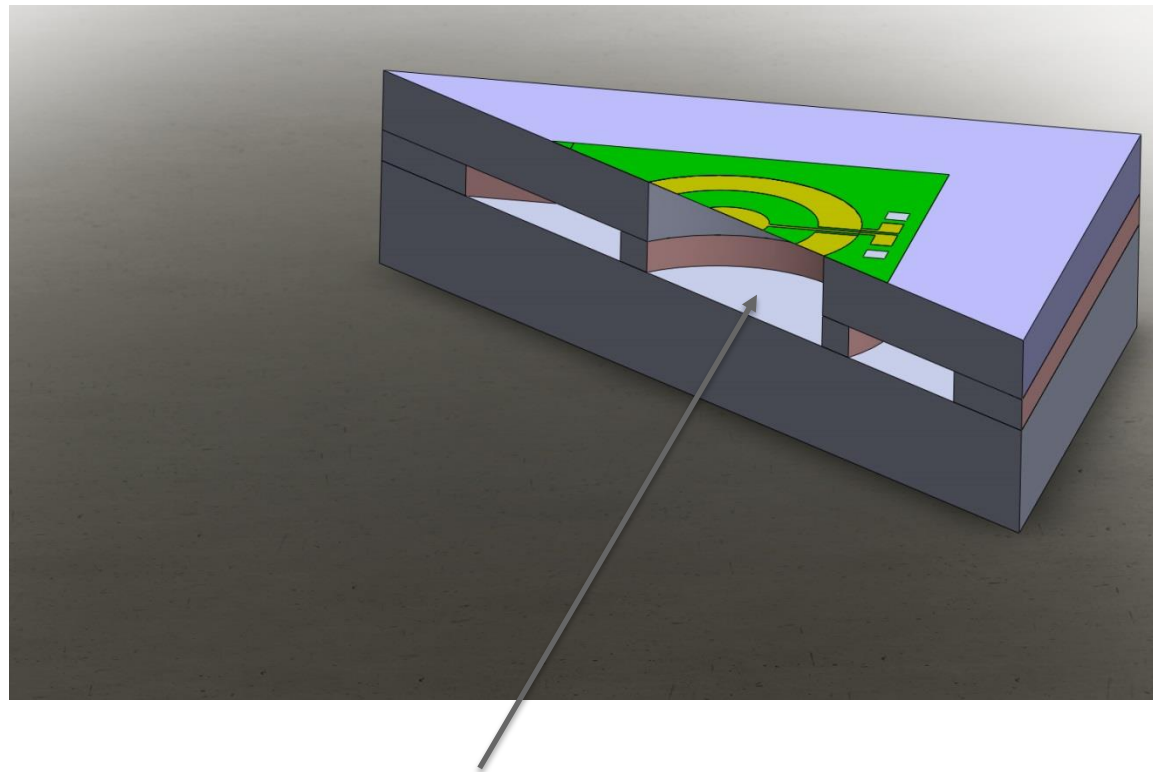


Reference Device Open to Atmosphere on Top and Bottom



Cluster Prototype Assembly

Harsh Environment Sensor Cluster



Sealed Cavity of Pressure Sensor

- **Sensor Cluster for**
 - Energy & Power / Gas Turbine
 - Transportation / Automobile Engine
 - Landslide Prediction / Built Infrastructure
- **Common Fabrication Process**
- **Many Sensors on One Chip**
- **Sensor Signal and Packaging are the Next Challenges**
- **Seeking Industrial Collaboration**



Acknowledgements



Harsh Environment Sensor Cluster

- **BSAC**
- **UC Berkeley Nanolab**
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- **Ms. Kirti Mansukhani**
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- **Mr. Wei-Cheng Lien**
- **Ms. Nuo Zhang**
- **Mr. Ting-Ta “Ernest” Yen**
- **Mr. Chih-Ming “Gimmy” Lin**



Conclusion

Harsh Environment Sensor Cluster

Thank You!

